

CLAIMS

1. A semiconductor device, comprising:
 - a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;
 - an extended adhesive material layer disposed on the top side of the base carrier, the adhesive material layer covering the central area and a large portion of the peripheral area of the base carrier top surface; and
 - an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.
2. The semiconductor device of claim 1, wherein the base carrier comprises a paddle.
3. The semiconductor device of claim 2, further comprising a leadframe to which bonding pads of the integrated circuit device are electrically connected.
4. The semiconductor device of claim 3, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.
5. The semiconductor device of claim 3, wherein the device is an exposed pad type packaged device.
6. A semiconductor device, comprising:
 - a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;

an adhesive material layer disposed on the top side of the base carrier, wherein the adhesive material layer is dispensed on the top side of the base carrier in an "X" shaped pattern, the "X" shaped pattern including two bisecting lines, wherein the two bisecting lines extend beyond the central area and into the peripheral area of the base carrier top surface; and

an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.

7. The semiconductor device of claim 6, wherein the "X" shaped pattern of adhesive material further includes a first line extending from a middle part of the peripheral area of a first side of the base carrier to a middle part of the peripheral area of a second, opposing side of the base carrier such that the adhesive material layer forms a six pointed star.

8. The semiconductor device of claim 7, wherein the "X" shaped pattern of adhesive material further includes a second line extending from a middle part of the peripheral area of a third side of the base carrier to a middle part of the peripheral area of a fourth, opposing side of the base carrier such that the adhesive material layer forms an eight pointed star.

9. The semiconductor device of claim 6, wherein the base carrier comprises a paddle.

10. The semiconductor device of claim 9, further comprising a leadframe to which bonding pads of the integrated circuit device are electrically connected.

11. The semiconductor device of claim 10, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.

12. The semiconductor device of claim 10, wherein the semiconductor device comprises an exposed pad type packaged device.

13. A method of attaching an integrated circuit die to a base carrier comprising the steps of:

dispensing an adhesive material onto a central area of a top surface of the base carrier, wherein the central area is sized to receive the integrated circuit die and the central area is surrounded by a peripheral area; and

attaching a bottom surface of the integrated circuit die to the central area on the top surface of the base carrier with the adhesive material, wherein the adhesive material dispensed onto the top surface of the base carrier extends well into the peripheral area of the base carrier top surface.

14. The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the dispensed adhesive material covers substantially the entire top surface of the base carrier.

15. The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the adhesive material is dispensed onto the base carrier top surface in a predetermined pattern.

16. The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an "X" pattern.

17. The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises a six point star pattern.

18. The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an eight point star pattern.